

Features

- ESD protected:1500V
- High Dense Cell Design For Extremely Low RDS(ON)
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

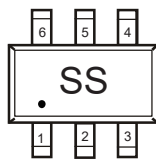
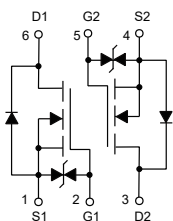
Maximum Ratings

- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature: -55°C to +150°C
- Thermal Resistance: 395°C/W Junction to Ambient^(Note 2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	50	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$	0.22
		$T_A=100^\circ\text{C}$	0.14
Pulsed Drain Current ^(Note 3)	I_{DM}	0.88	A
Total Power Dissipation ^(Note 4)	P_D	0.32	W

- Note:
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.
 3. Repetitive rating; pulse width limited by max. junction temperature.
 4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

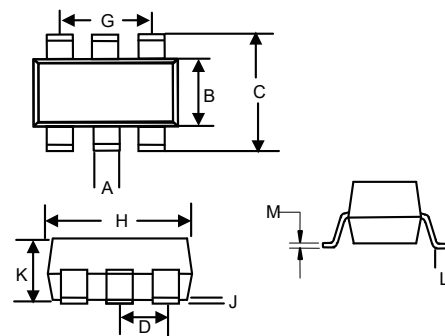
Internal Structure and Marking Code



Dot denotes Pin1

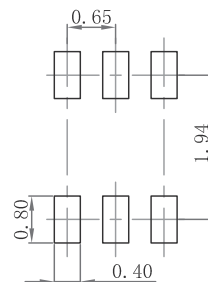
Dual N-Channel MOSFET

SOT-363



DIM	DIMENSIONS				NOTE
	INCHES		MM		
A	0.006	0.014	0.15	0.35	
B	0.045	0.053	1.15	1.35	
C	0.079	0.096	2.00	2.45	
D	0.026		0.65		TYP.
G	0.047	0.055	1.20	1.40	
H	0.071	0.087	1.80	2.20	
J	-----	0.004	-----	0.10	
K	0.031	0.043	0.80	1.10	
L	0.010	0.018	0.26	0.46	
M	0.003	0.006	0.08	0.15	

Suggested Solder Pad Layout



ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	50			V
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.8	1.0	1.45	V
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 10	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=48V, V_{GS}=0V$			1	μA
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=0.5A$		1.1	1.6	Ω
		$V_{GS}=4.5V, I_D=0.1A$		1.2	2.5	
		$V_{GS}=2.5V, I_D=0.1A$		1.8	3.8	
Forward Transconductance	g_{FS}	$V_{DS}=10V, I_D=0.1A$		325		mS
Gate Resistance	R_g	f=1 MHz, Open drain		84		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				0.22	A
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_S=0.5A$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F=0.5A, dI_F/dt=100A/\mu s$		9.4		ns
Reverse Recovery Charge	Q_{rr}			2.2		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$		29.5		μF
Output Capacitance	C_{oss}			4.4		
Reverse Transfer Capacitance	C_{rss}			3		
Total Gate Charge	Q_g	$V_{DS}=25V, V_{GS}=10V, I_D=0.5A$		1.2		nC
Gate-Source Charge	Q_{gs}			0.32		
Gate-Drain Charge	Q_{gd}			0.16		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=25V, V_{GS}=10V, R_{GEN}=25\Omega, I_D=0.5A$		3.3		ns
Turn-On Rise Time	t_r			3		
Turn-Off Delay Time	$t_{d(off)}$			12		
Turn-Off Fall Time	t_f			9		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

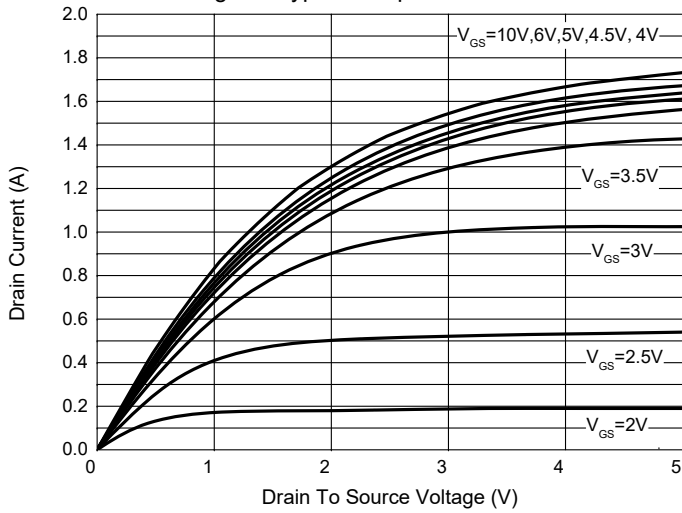


Fig. 2 - Transfer Characteristics

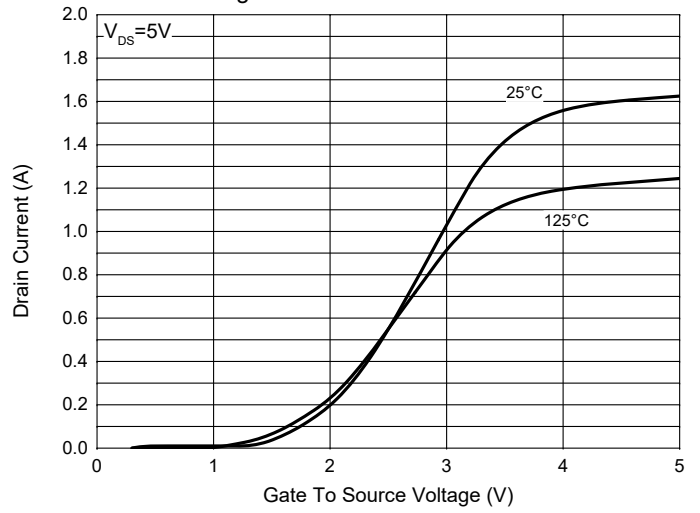


Fig. 3 - $R_{DS(ON)} - V_{GS}$

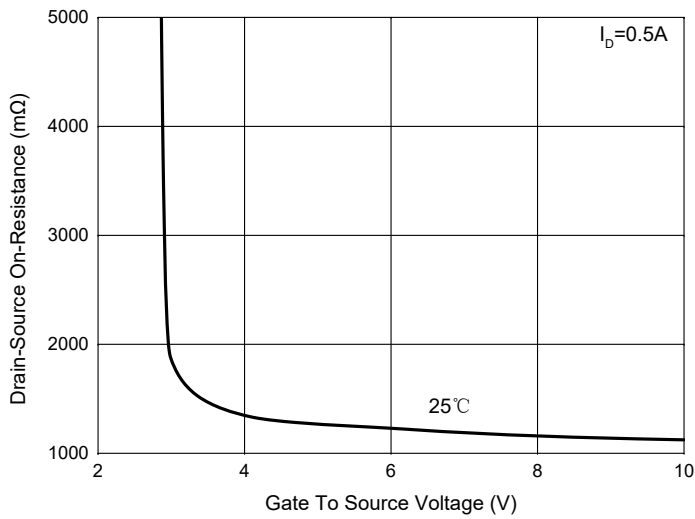


Fig. 4 - $R_{DS(ON)} - I_D$

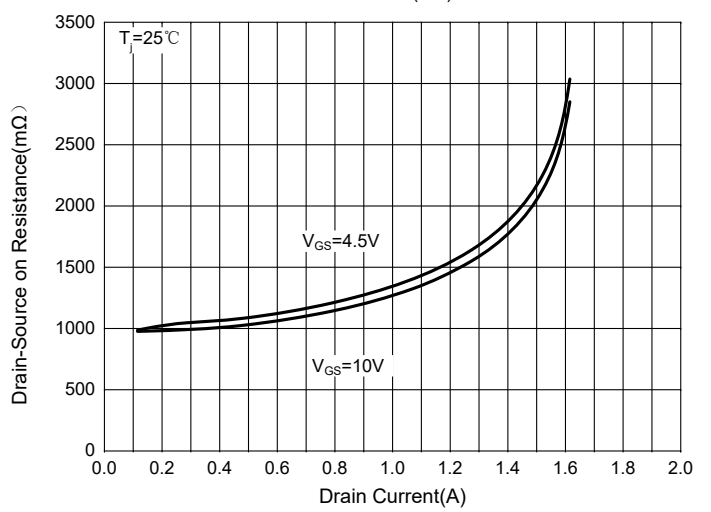


Fig. 5 - Capacitance Characteristics

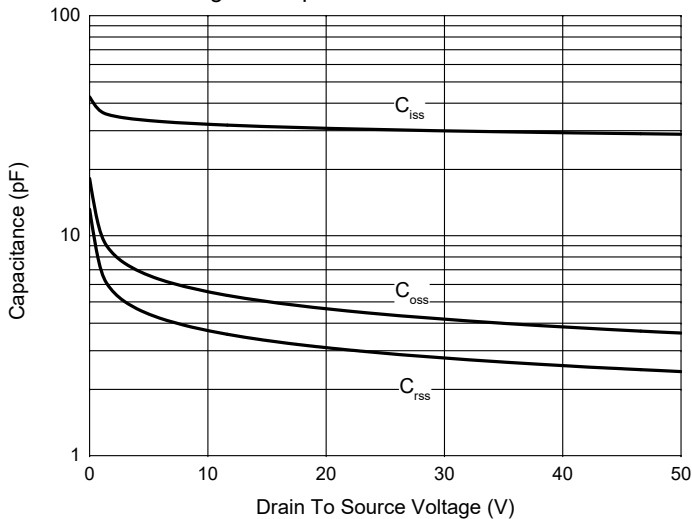
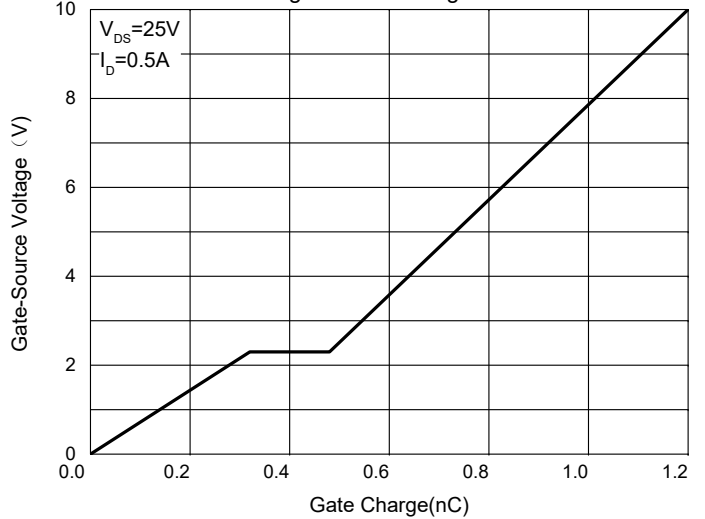


Fig. 6 - GateCharge



Curve Characteristics

Fig. 7 - Normalized Threshold Voltage

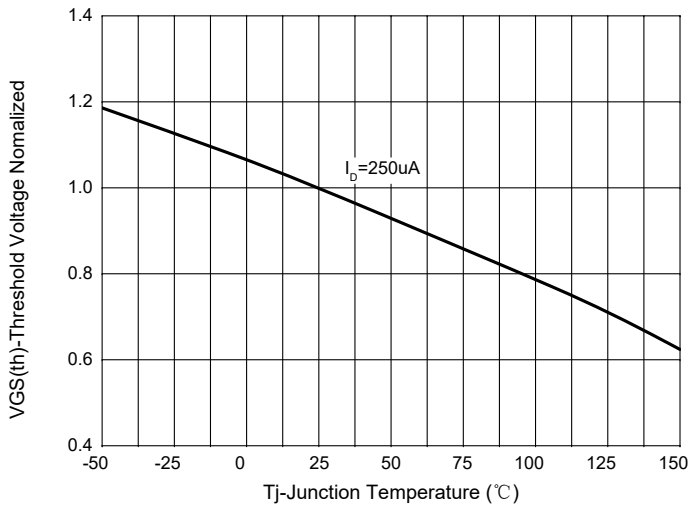


Fig.8-Normalized On Resistance Characteristics

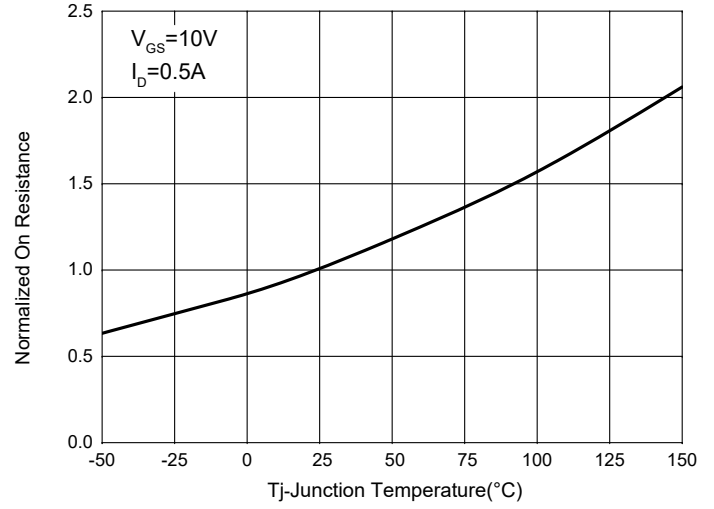


Fig.9 - I_S—V_{SD}

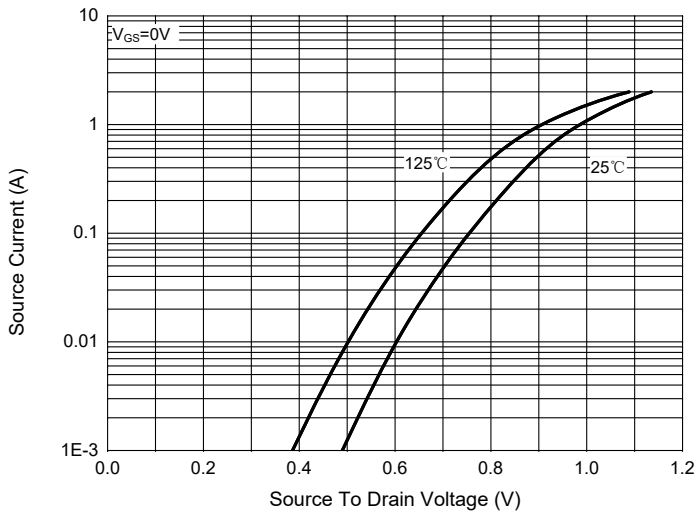


Fig. 10 - Drain Current

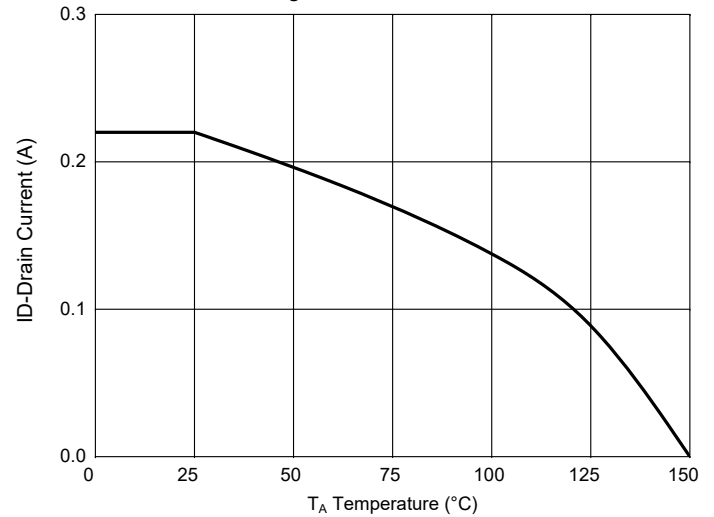
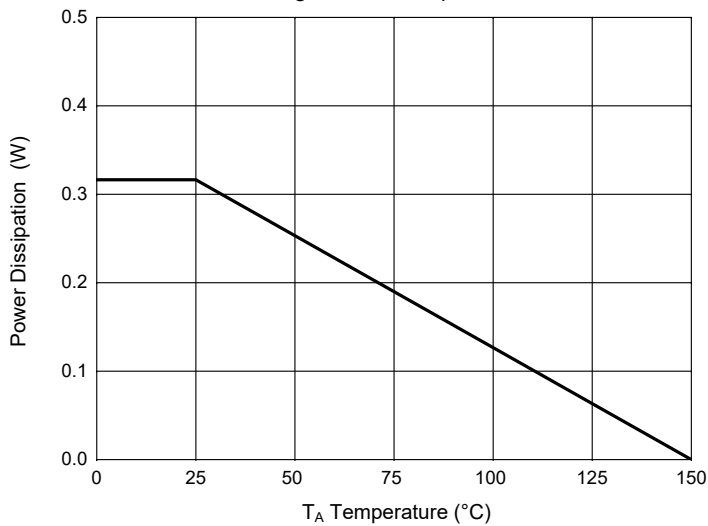


Fig.11-PD Dissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

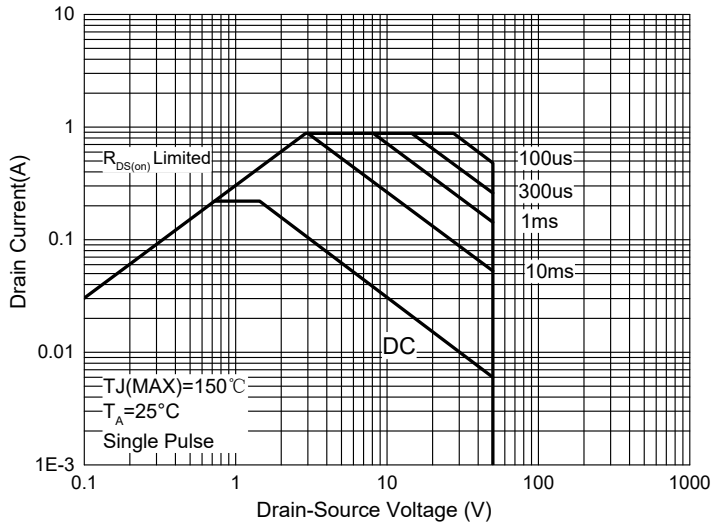
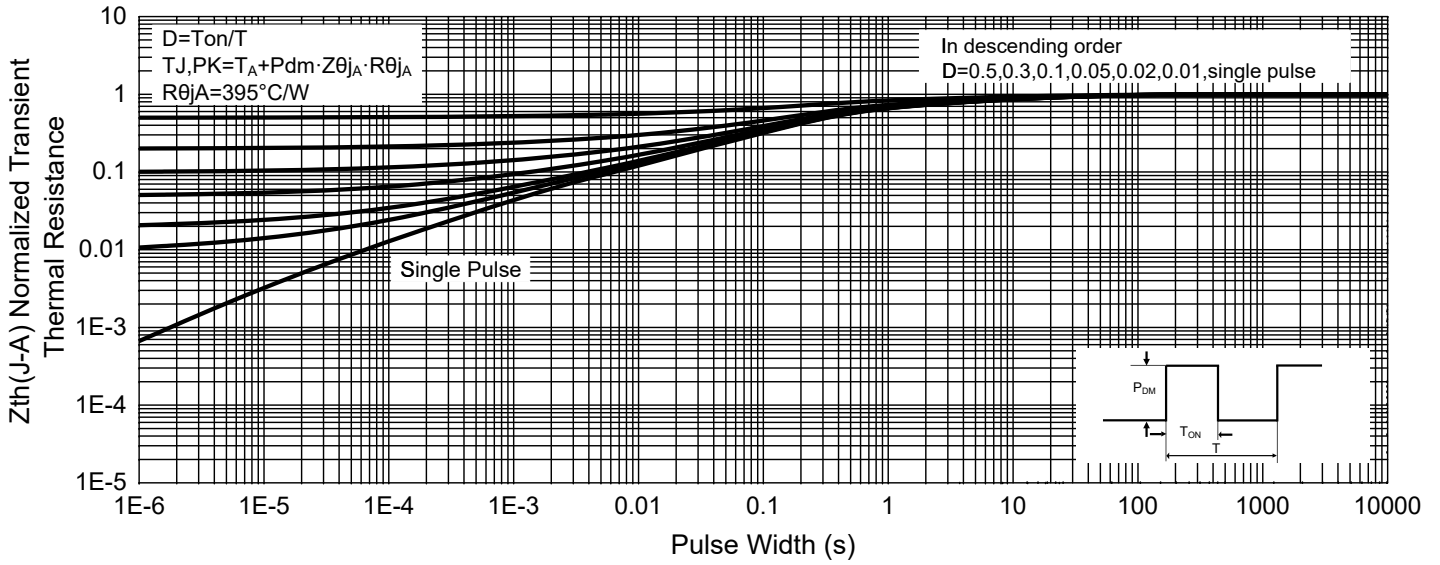


Fig. 13 -Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:3Kpcs/Reel
Part Number-TPQ2	Tape&Reel:3Kpcs/Reel

For packaging details, go to our website at <https://www.mccsemi.com/pdf/ProductPackaging/SOT-363%20Package.pdf>

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